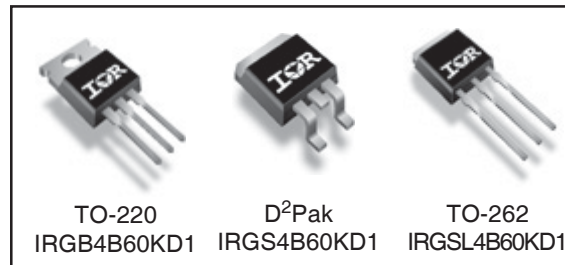
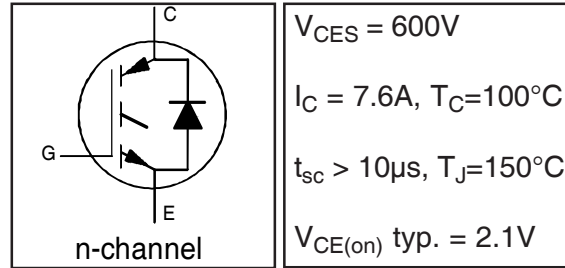


Features

- Low VCE (on) Non Punch Through IGBT Technology.
- 10µs Short Circuit Capability.
- Square RBSOA.
- Positive VCE (on) Temperature Coefficient.
- Maximum Junction Temperature rated at 175°C.
- Lead-Free

Benefits

- Benchmark Efficiency for Motor Control.
- Rugged Transient Performance.
- Low EMI.
- Excellent Current Sharing in Parallel Operation.



Absolute Maximum Ratings

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Voltage	600	V
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	11	A
$I_C @ T_C = 100^\circ C$	Continuous Collector Current	7.6	
I_{CM}	Pulse Collector Current (Ref.Fig.C.T.5)	22	
I_{LM}	Clamped Inductive Load current ①	22	
$I_F @ T_C = 25^\circ C$	Diode Continuous Forward Current	11	
$I_F @ T_C = 100^\circ C$	Diode Continuous Forward Current	6.7	V
I_{FM}	Diode Maximum Forward Current	22	
V_{GE}	Gate-to-Emitter Voltage	± 20	
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	63	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	31	
T_J	Operating Junction and	-55 to +175	$^\circ C$
T_{STG}	Storage Temperature Range		
	Storage Temperature Range, for 10 sec.	300 (0.063 in. (1.6mm) from case)	

Thermal / Mechanical Characteristics

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case- IGBT	—	—	2.4	$^\circ C/W$
$R_{\theta JC}$	Junction-to-Case- Diode	—	—	6.1	
$R_{\theta CS}$	Case-to-Sink, flat, greased surface	—	0.50	—	
$R_{\theta JA}$	Junction-to-Ambient	—	—	62	
$R_{\theta JA}$	Junction-to-Ambient (PCB Mount, steady state)②	—	—	40	
Wt	Weight	—	1.44	—	g

IRGB/S/SL4B60KD1PbF

International
IR Rectifier

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions	Ref.Fig.
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage	600	—	—	V	$V_{GE} = 0V, I_C = 500\mu A$	
$\Delta V_{(BR)CES}/\Delta T_J$	Temperature Coeff. of Breakdown Voltage	—	0.28	—	V/ $^\circ\text{C}$	$V_{GE} = 0V, I_C = 1mA (25^\circ\text{C}-150^\circ\text{C})$	
$V_{CE(on)}$	Collector-to-Emitter Voltage	—	2.1	2.5	V	$I_C = 4.0A, V_{GE} = 15V, T_J = 25^\circ\text{C}$	5,6,7
		—	2.5	2.8		$I_C = 4.0A, V_{GE} = 15V, T_J = 150^\circ\text{C}$	9,10,11
		—	2.6	2.9		$I_C = 4.0A, V_{GE} = 15V, T_J = 175^\circ\text{C}$	
$V_{GE(th)}$	Gate Threshold Voltage	3.5	4.5	5.5	V	$V_{CE} = V_{GE}, I_C = 250\mu A$	9,10,11
$\Delta V_{GE(th)}/\Delta T_J$	Threshold Voltage temp. coefficient	—	-8.1	—	mV/ $^\circ\text{C}$	$V_{CE} = V_{GE}, I_C = 1mA (25^\circ\text{C}-150^\circ\text{C})$	12
g_{fe}	Forward Transconductance	—	1.7	—	S	$V_{CE} = 50V, I_C = 4.0A, PW = 80\mu s$	
I_{CES}	Zero Gate Voltage Collector Current	—	1.0	150	μA	$V_{GE} = 0V, V_{CE} = 600V$	
		—	136	600		$V_{GE} = 0V, V_{CE} = 600V, T_J = 150^\circ\text{C}$	
		—	722	2400		$V_{GE} = 0V, V_{CE} = 600V, T_J = 175^\circ\text{C}$	
V_{FM}	Diode Forward Voltage Drop	—	1.4	2.0	V	$I_F = 4.0A$	8
		—	1.3	1.8		$I_F = 4.0A, T_J = 150^\circ\text{C}$	
		—	1.2	1.7		$I_F = 4.0A, T_J = 175^\circ\text{C}$	
I_{GES}	Gate-to-Emitter Leakage Current	—	—	± 100	nA	$V_{GE} = \pm 20V$	

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions	Ref.Fig.
Q_g	Total Gate Charge (turn-on)	—	12	—	nC	$I_C = 4.0A$	23
Q_{ge}	Gate-to-Emitter Charge (turn-on)	—	1.7	—		$V_{CC} = 400V$	CT1
Q_{gc}	Gate-to-Collector Charge (turn-on)	—	6.5	—		$V_{GE} = 15V$	
E_{on}	Turn-On Switching Loss	—	73	80	μJ	$I_C = 4.0A, V_{CC} = 400V$	CT4
E_{off}	Turn-Off Switching Loss	—	47	53		$V_{GE} = 15V, R_G = 100\Omega, L = 2.5mH$	
E_{tot}	Total Switching Loss	—	120	130		$T_J = 25^\circ\text{C} \text{ ③}$	
$t_{d(on)}$	Turn-On delay time	—	22	28	ns	$I_C = 4.0A, V_{CC} = 400V$	CT4
t_r	Rise time	—	18	23		$V_{GE} = 15V, R_G = 100\Omega, L = 2.5mH$	
$t_{d(off)}$	Turn-Off delay time	—	100	110		$T_J = 25^\circ\text{C}$	
t_f	Fall time	—	66	80	μJ	$I_C = 4.0A, V_{CC} = 400V$	CT4
E_{on}	Turn-On Switching Loss	—	130	150		$V_{GE} = 15V, R_G = 100\Omega, L = 2.5mH$	13,15
E_{off}	Turn-Off Switching Loss	—	83	140		$T_J = 150^\circ\text{C} \text{ ③}$	WF1,WF2
E_{tot}	Total Switching Loss	—	220	280	ns	$I_C = 4.0A, V_{CC} = 400V$	14,16
$t_{d(on)}$	Turn-On delay time	—	22	27		$V_{GE} = 15V, R_G = 100\Omega, L = 2.5mH$	CT4
t_r	Rise time	—	18	22		$T_J = 150^\circ\text{C}$	WF1
$t_{d(off)}$	Turn-Off delay time	—	120	130	pF		WF2
t_f	Fall time	—	79	89			
C_{ies}	Input Capacitance	—	190	—		$V_{GE} = 0V$	22
C_{oes}	Output Capacitance	—	25	—	pF	$V_{CC} = 30V$	
C_{res}	Reverse Transfer Capacitance	—	6.2	—		$f = 1.0MHz$	
RBSOA	Reverse Bias Safe Operating Area	FULL SQUARE				$T_J = 150^\circ\text{C}, I_C = 22A, V_p = 600V$ $V_{CC}=500V, V_{GE} = +15V \text{ to } 0V, R_G = 100\Omega$	4 CT2
SCSOA	Short Circuit Safe Operating Area	10	—	—	μs	$T_J = 150^\circ\text{C}, V_p = 600V, R_G = 100\Omega$ $V_{CC}=360V, V_{GE} = +15V \text{ to } 0V$	CT3 WF4
E_{rec}	Reverse Recovery Energy of the Diode	—	81	100	μJ	$T_J = 150^\circ\text{C}$	17,18,19
t_{rr}	Diode Reverse Recovery Time	—	93	—	ns	$V_{CC} = 400V, I_F = 4.0A, L = 2.5mH$	20,21
I_{rr}	Peak Reverse Recovery Current	—	6.3	7.9	A	$V_{GE} = 15V, R_G = 100\Omega$	CT4,WF3

Note ① to ③ are on page 16

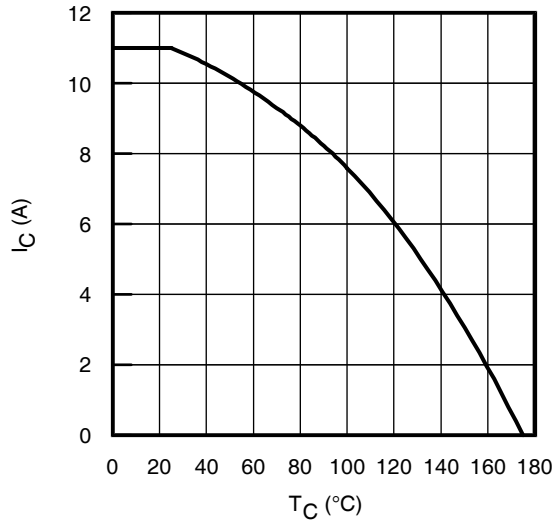


Fig. 1 - Maximum DC Collector Current vs. Case Temperature

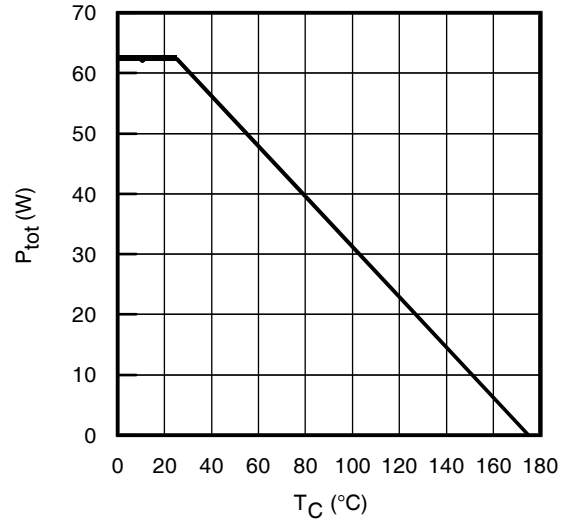


Fig. 2 - Power Dissipation vs. Case Temperature

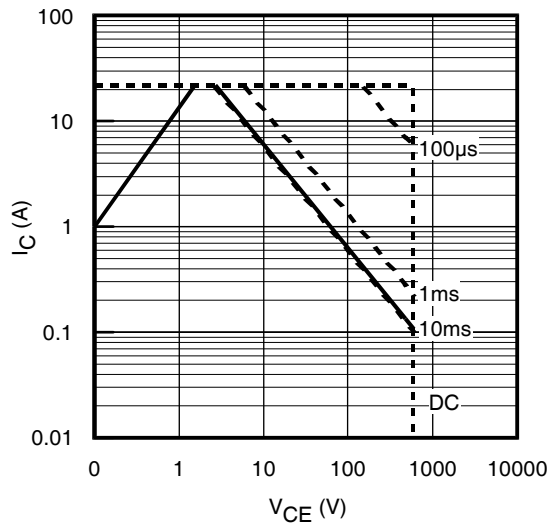


Fig. 3 - Forward SOA
 $T_C = 25^{\circ}\text{C}$; $T_J \leq 150^{\circ}\text{C}$

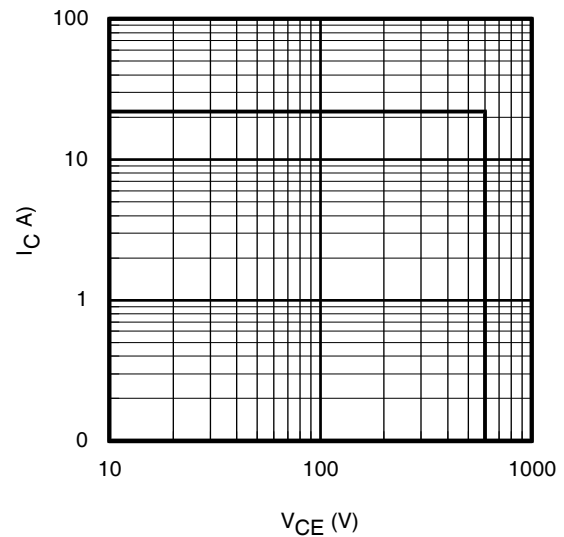


Fig. 4 - Reverse Bias SOA
 $T_J = 150^{\circ}\text{C}$; $V_{GE} = 15\text{V}$

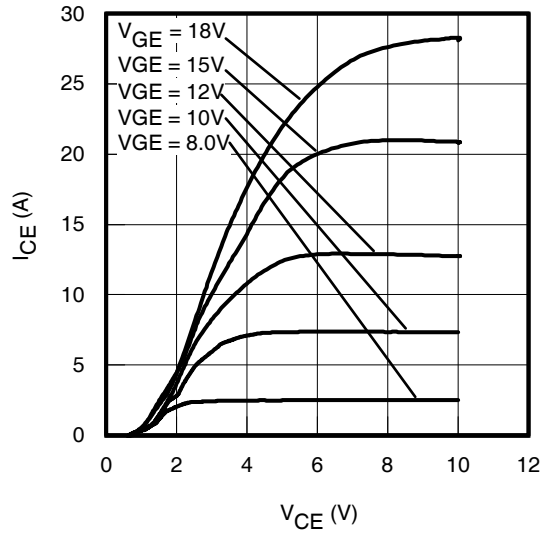


Fig. 5 - Typ. IGBT Output Characteristics
T_j = -40°C; tp = 80μs

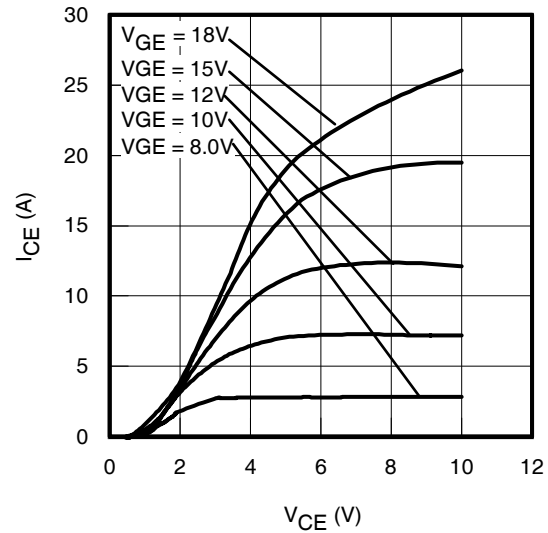


Fig. 6 - Typ. IGBT Output Characteristics
T_j = 25°C; tp = 80μs

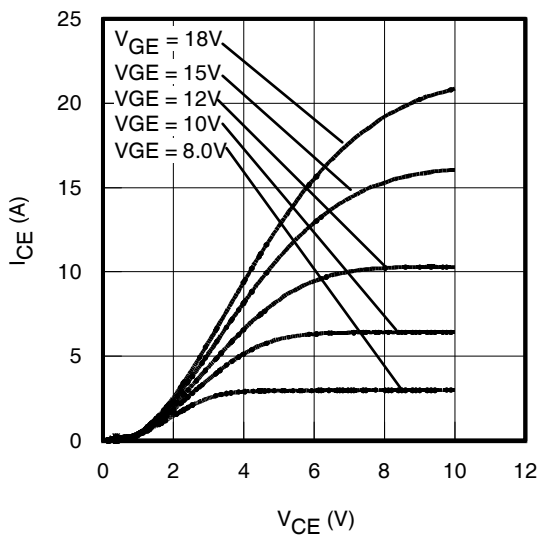


Fig. 7 - Typ. IGBT Output Characteristics
T_j = 150°C; tp = 80μs

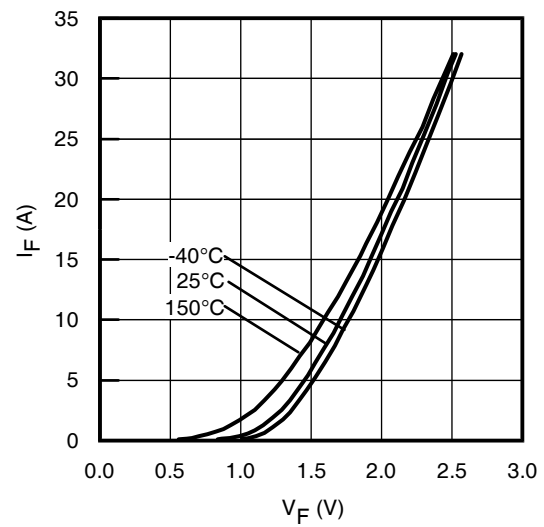


Fig. 8 - Typ. Diode Forward Characteristics
tp = 80μs

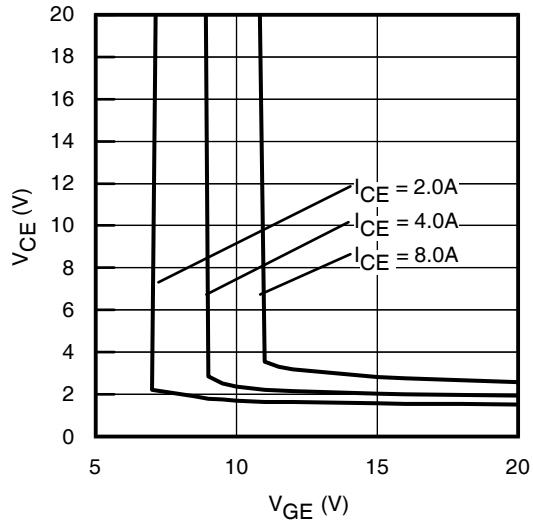


Fig. 9 - Typical V_{CE} vs. V_{GE}
 $T_J = -40^{\circ}\text{C}$

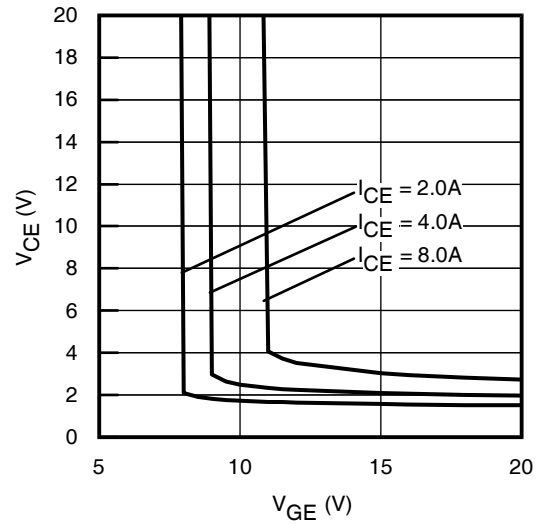


Fig. 10 - Typical V_{CE} vs. V_{GE}
 $T_J = 25^{\circ}\text{C}$

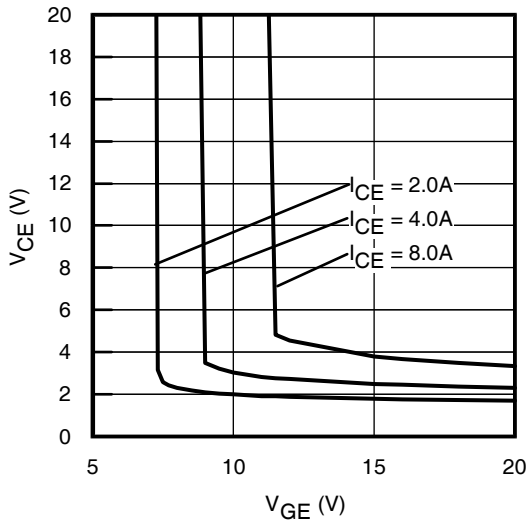


Fig. 11 - Typical V_{CE} vs. V_{GE}
 $T_J = 150^{\circ}\text{C}$

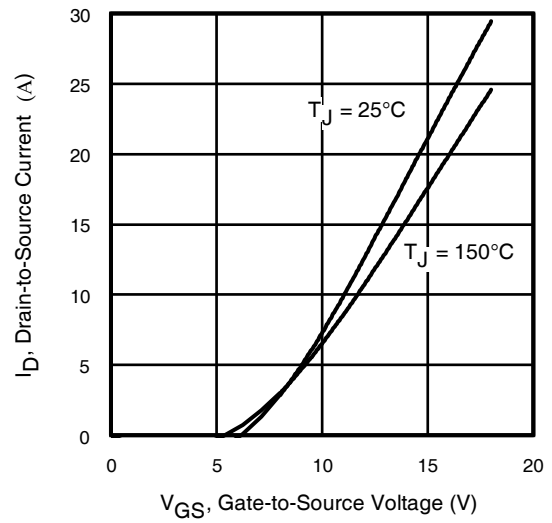


Fig. 12 - Typ. Transfer Characteristics
 $V_{CE} = 360\text{V}$; $t_p = 10\mu\text{s}$

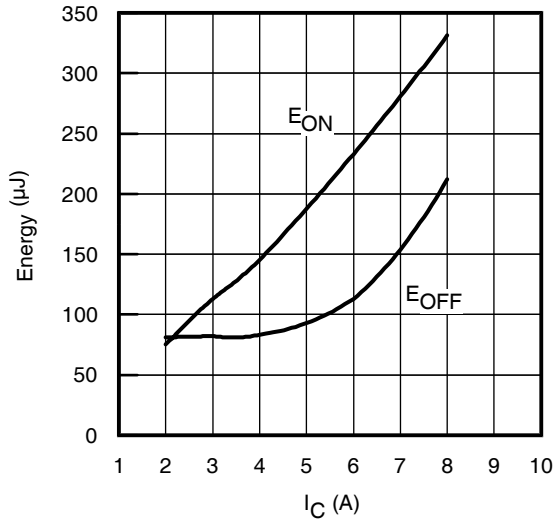


Fig. 13 - Typ. Energy Loss vs. I_C
 $T_J = 150^\circ\text{C}$; $L=2.5\text{mH}$; $V_{CE}= 400\text{V}$,
 $R_G= 100\Omega$; $V_{GE}= 15\text{V}$

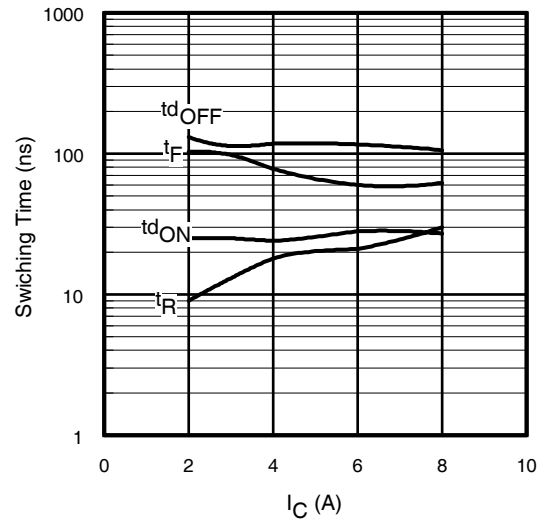


Fig. 14 - Typ. Switching Time vs. I_C
 $T_J = 150^\circ\text{C}$; $L=2.5\text{mH}$; $V_{CE}= 400\text{V}$
 $R_G= 100\Omega$; $V_{GE}= 15\text{V}$

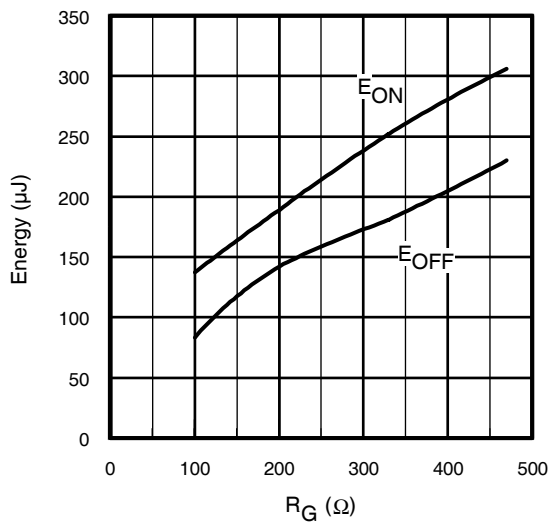


Fig. 15 - Typ. Energy Loss vs. R_G
 $T_J = 150^\circ\text{C}$; $L=2.5\text{mH}$; $V_{CE}= 400\text{V}$
 $I_{CE}= 4.0\text{A}$; $V_{GE}= 15\text{V}$

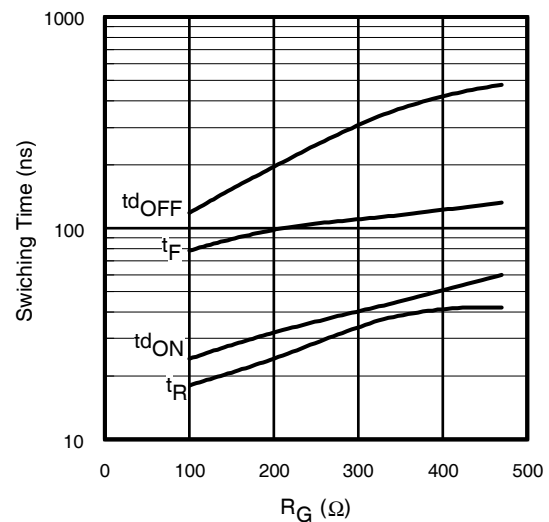


Fig. 16 - Typ. Switching Time vs. R_G
 $T_J = 150^\circ\text{C}$; $L=2.5\text{mH}$; $V_{CE}= 400\text{V}$
 $I_{CE}= 4.0\text{A}$; $V_{GE}= 15\text{V}$

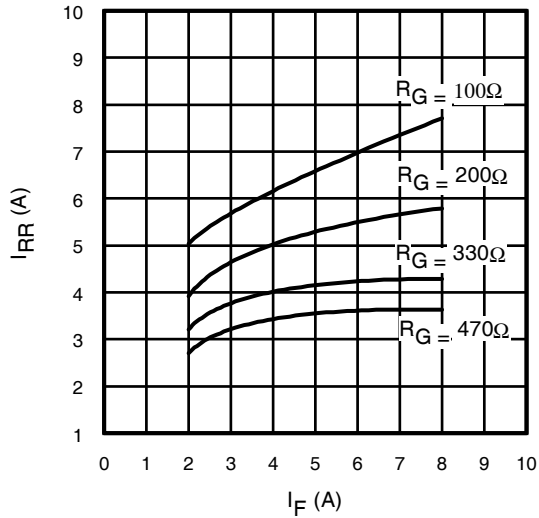


Fig. 17 - Typical Diode I_{RR} vs. I_F
 $T_J = 150^\circ\text{C}$

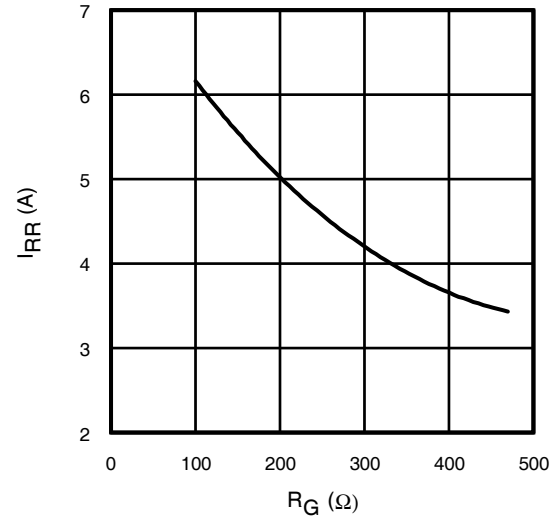


Fig. 18 - Typical Diode I_{RR} vs. R_G
 $T_J = 150^\circ\text{C}$; $I_F = 4.0\text{A}$

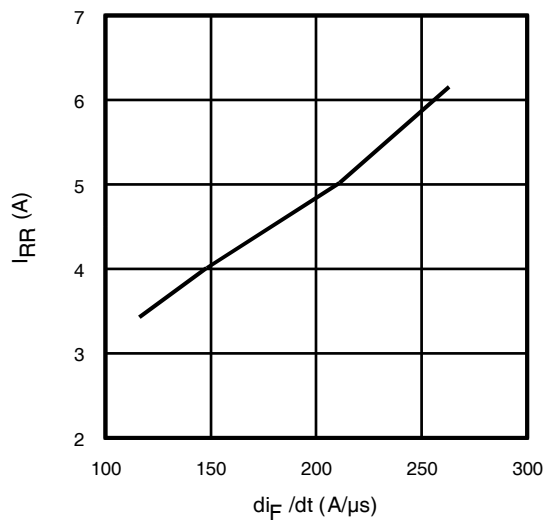


Fig. 19 - Typical Diode I_{RR} vs. di_F/dt
 $V_{CC} = 400\text{V}$; $V_{GE} = 15\text{V}$;
 $I_F = 4.0\text{A}$; $T_J = 150^\circ\text{C}$

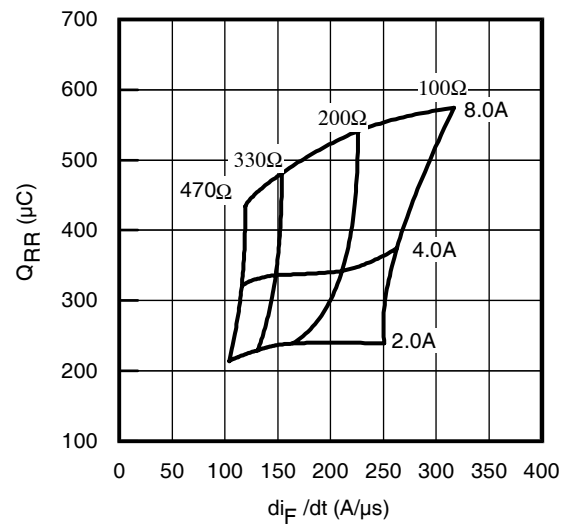


Fig. 20 - Typical Diode Q_{RR}
 $V_{CC} = 400\text{V}$; $V_{GE} = 15\text{V}$; $T_J = 150^\circ\text{C}$

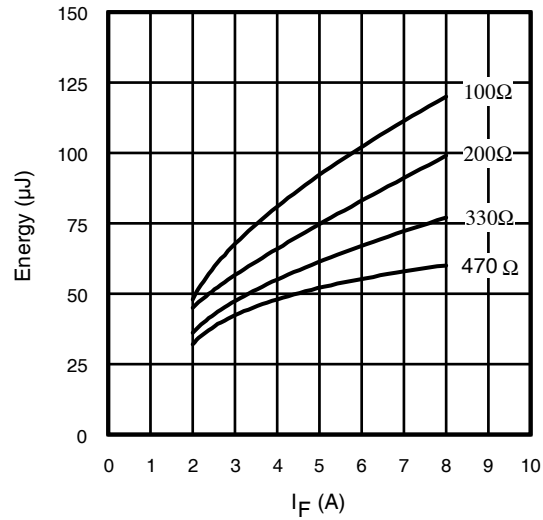


Fig. 21 - Typical Diode E_{RR} vs. I_F
 $T_J = 150^\circ\text{C}$

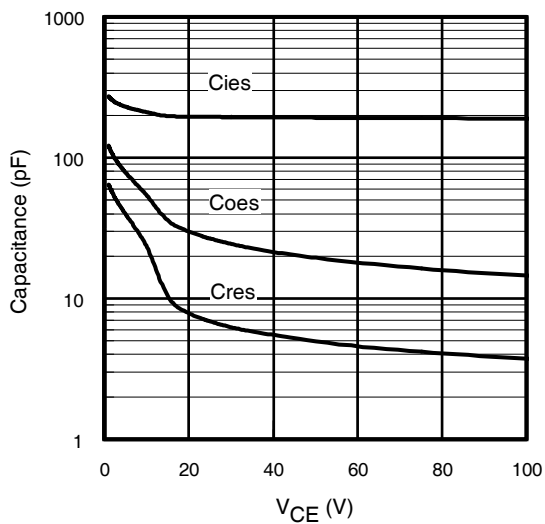


Fig. 22- Typ. Capacitance vs. V_{CE}
 $V_{GE} = 0\text{V}$; $f = 1\text{MHz}$

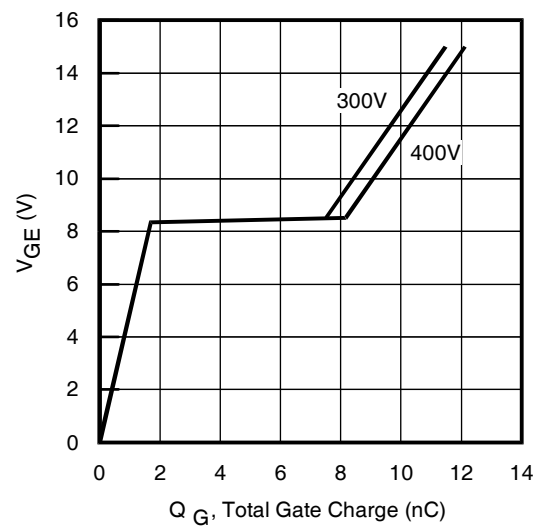


Fig. 23 - Typical Gate Charge vs. V_{GE}
 $I_{CE} = 4.0\text{A}$; $L = 3150\mu\text{H}$

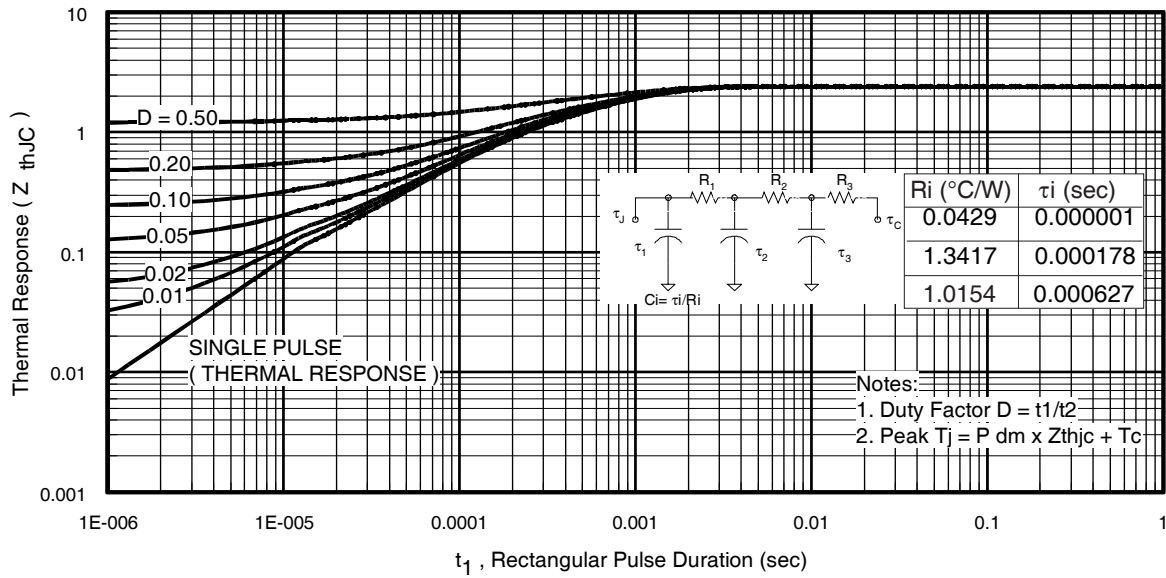


Fig 24. Maximum Transient Thermal Impedance, Junction-to-Case (IGBT)

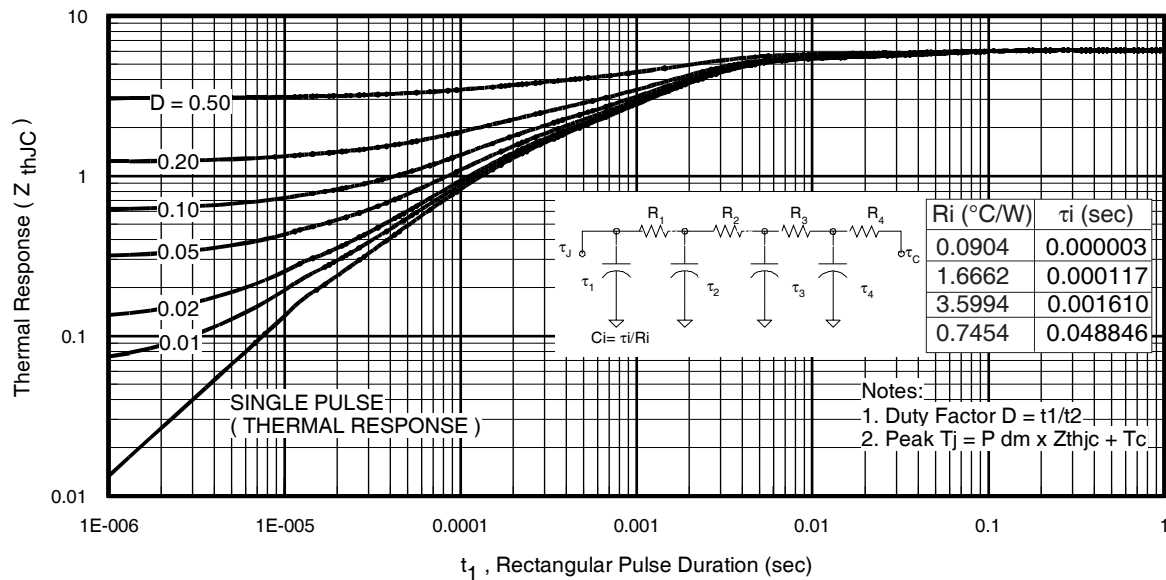


Fig 25. Maximum Transient Thermal Impedance, Junction-to-Case (DIODE)

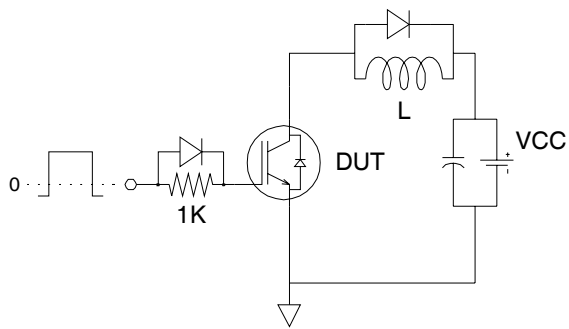


Fig.C.T.1 - Gate Charge Circuit (turn-off)

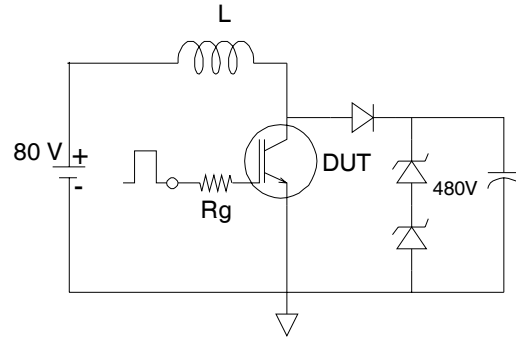


Fig.C.T.2 - RBSOA Circuit

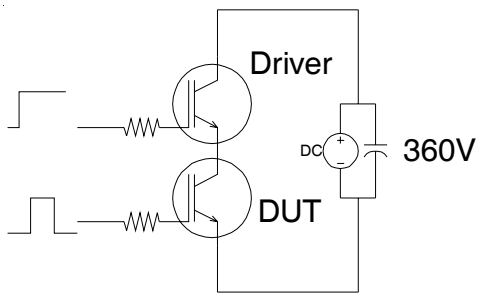


Fig.C.T.3 - S.C.SOA Circuit

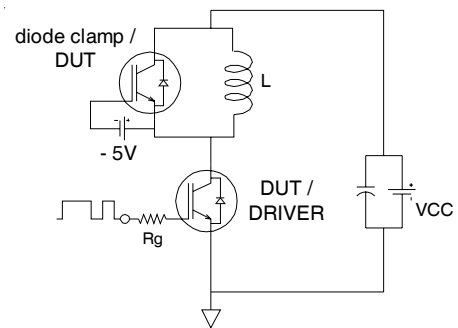


Fig.C.T.4 - Switching Loss Circuit

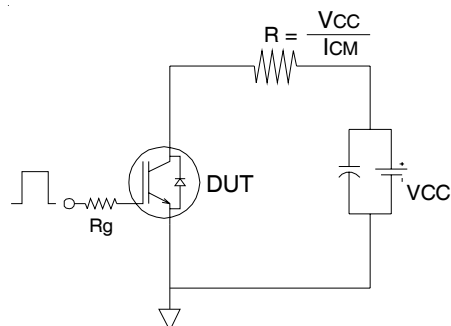


Fig.C.T.5 - Resistive Load Circuit

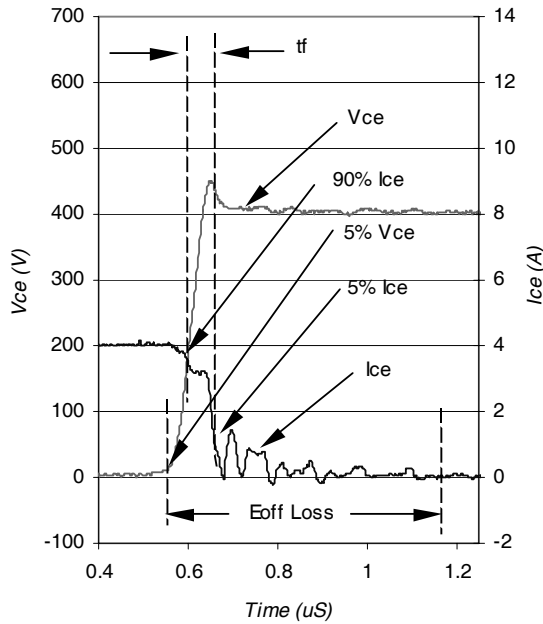


Fig. WF1- Typ. Turn-off Loss Waveform
@ $T_J = 150^\circ\text{C}$ using Fig. CT.4

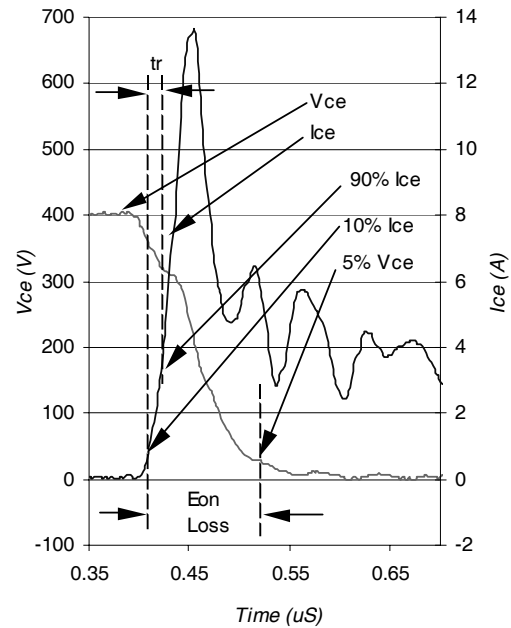


Fig. WF2- Typ. Turn-on Loss Waveform
@ $T_J = 150^\circ\text{C}$ using Fig. CT.4

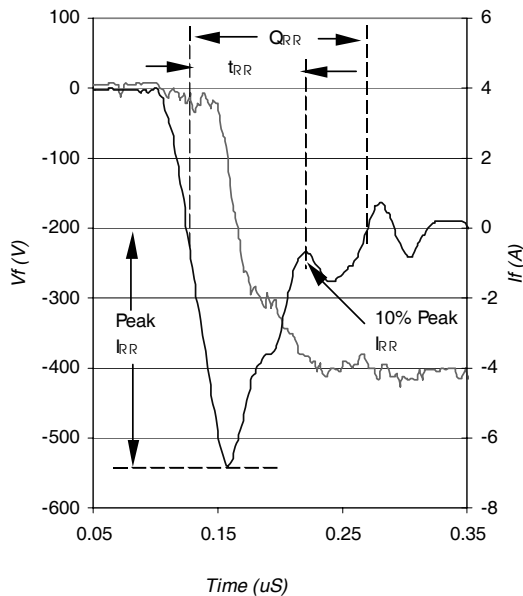


Fig. WF3- Typ. Diode Recovery Waveform
@ $T_J = 150^\circ\text{C}$ using Fig. CT.4

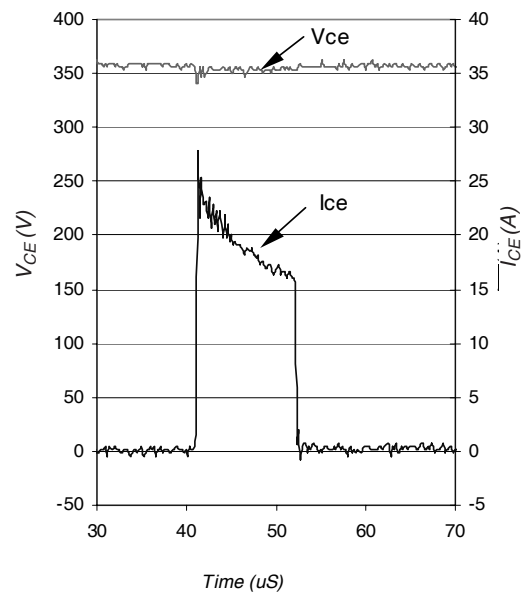
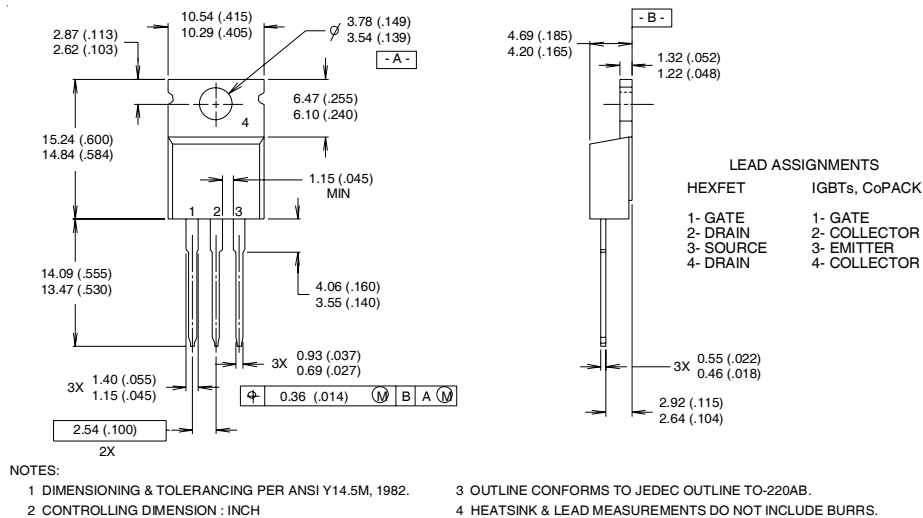


Fig. WF4- Typ. S.C Waveform
@ $T_C = 150^\circ\text{C}$ using Fig. CT.3

TO-220AB Package Outline

Dimensions are shown in millimeters (inches)



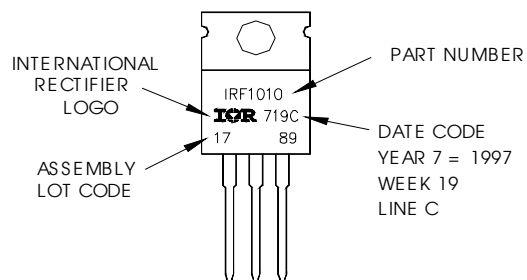
TO-220AB Part Marking Information

EXAMPLE: THIS IS AN IRF1010

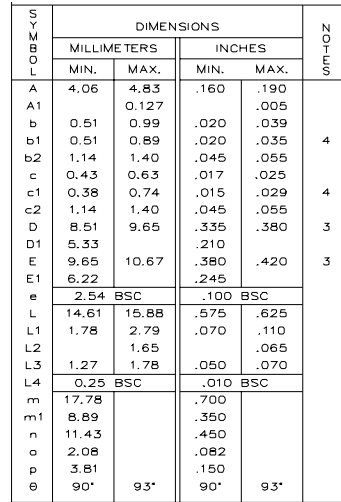
LOT CODE 1789

ASSEMBLED ON WW 19, 1997
IN THE ASSEMBLY LINE "C"

Note: "P" in assembly line
position indicates "Lead-Free"



Dimensions are shown in millimeters (inches)



HEXFET	IGBTs, CoPACK	DIODES
1.- GATE	1.- GATE	1.- ANODE *
2.- DRAIN	2.- COLLECTOR	2.- CATHODE
3.- SOURCE	3.- EMITTER	3.- ANODE

- PART DEPENDENT.

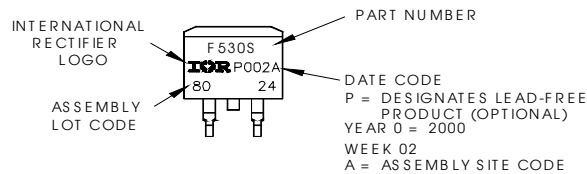
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
 3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH, MOLD FLASH SHALL NOT EXCEED 0.127 [.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
 4.  DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
 5. CONTROLLING DIMENSION: INCH.

EXAMPLE: THIS IS AN IRF530S WITH
LOT CODE 8024
ASSEMBLED ON WW 02, 2000
IN THE ASSEMBLY LINE "L"

Diagram illustrating the markings on the F530S diode package:

- INTERNATIONAL RECTIFIER LOGO**: Points to the IR logo on the package.
- PART NUMBER**: Points to the F530S marking.
- DATE CODE**: Points to the 002L marking.
- YEAR 0 = 2000**: Explains the date code format.
- WEEK 02**: Explains the date code format.
- ASSEMBLY LOT CODE**: Points to the 80 marking.
- 24**: Points to the marking on the package.

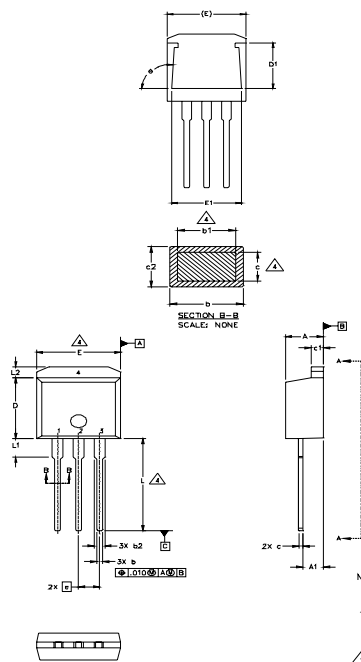
OR



IRGB/S/SL4B60KD1PbF

International
IR Rectifier

TO-262 Package Outline



SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	.160	.190	4
A1	2.03	2.92	.080	.115	
b	0.51	0.99	.020	.039	
b1	0.51	0.89	.020	.035	
b2	1.14	1.40	.045	.055	4
c	0.38	0.63	.015	.025	
c1	1.14	1.40	.045	.055	
c2	0.43	.063	.017	.029	
D	8.51	9.65	.335	.380	3
D1	5.33		.210		
E	9.65	10.67	.380	.420	3
E1	6.22		.245		
e	2.54 BSC		.100 BSC		
L	13.46	14.09	.530	.555	
L1	3.56	3.71	.140	.146	
L2		1.65		.065	

LEAD ASSIGNMENTS

HEXFET

- 1. - GATE
- 2. - DRAIN
- 3. - SOURCE
- 4. - DRAIN

IGBT

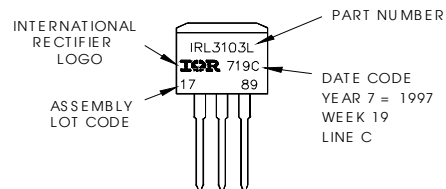
- 1 - GATE
- 2 - COLLECTOR
- 3 - EMITTER

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES]
 3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [0.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
 4. DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
 5. CONTROLLING DIMENSION: INCH.

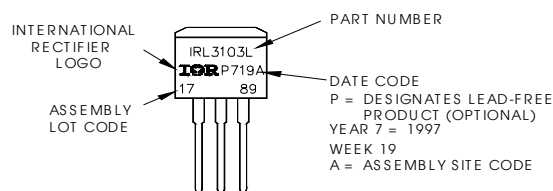
TO-262 Part Marking Information

EXAMPLE: THIS IS AN IRL3103L
LOT CODE 1789
ASSEMBLED ON WW 19, 1997
IN THE ASSEMBLY LINE "C"

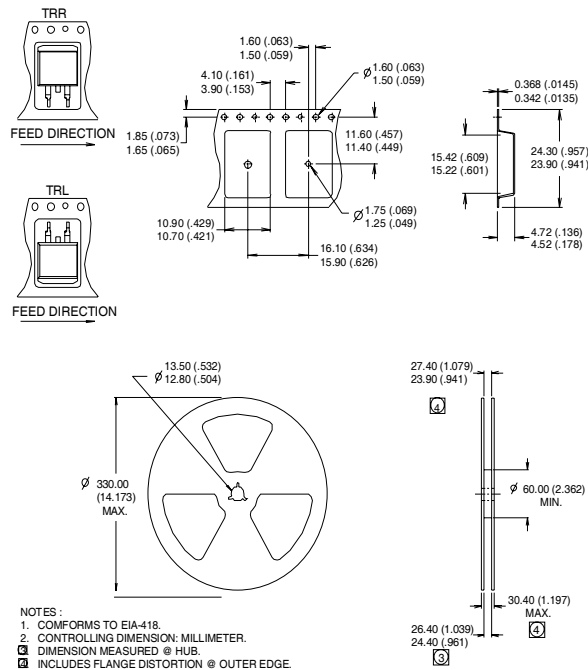
Note: "P" in assembly line position indicates "Lead-Free"



OR



D²Pak Tape & Reel Infomation



Notes:

- ① $V_{CC} = 80\% (V_{CES})$, $V_{GE} = 15V$, $L = 100\mu H$, $R_G = 100\Omega$.
- ② When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994.
- ③ Energy losses include "tail" and diode reverse recovery, using Diode FD059H06A5.

TO-220AB package is not recommended for Surface Mount Application.

Data and specifications subject to change without notice.
This product has been designed and qualified for Industrial market.
Qualification Standards can be found on IR's Web site.

International
IR Rectifier

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Visit us at www.irf.com for sales contact information. 08/04

Note: For the most current drawings please refer to the IR website at:
<http://www.irf.com/package/>